

ABSTRACT OF THE DISCLOSURE

A lead frame for a semiconductor device. The semiconductor device has a sheet with oppositely facing sides and a thickness between the oppositely facing sides. The sheet has first and second unit lead frames. Each unit lead frame has a support for a semiconductor chip and at least one lead space from the support. The sheet has a tie bar network which connects a) the support to the at least one lead on each of the first and second lead frames and b) the first and second lead frames, each to the other. The sheet has a dividing line along which the sheet can be cut to separate the first and second lead frames from each other. The tie bar network consists of at least one tie bar extending along a substantial length of the dividing line. The support has a first thickness between the oppositely facing sides of the sheet. The at least one tie bar has a second thickness between the oppositely facing sides of the sheet over a substantial length of the dividing line that is less than the first thickness.